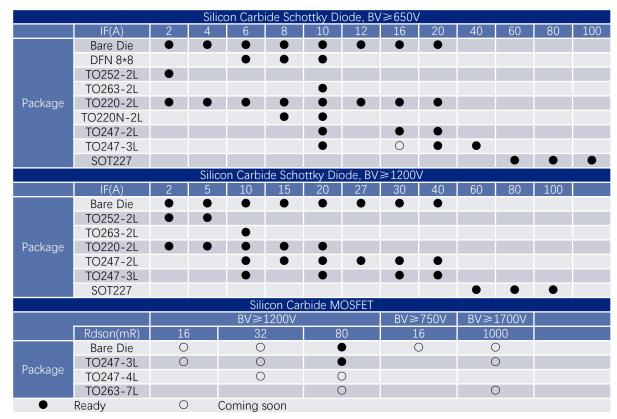
# Hunan Sanan Product List



#### SiC SBD Characteristic:

- Zero Reverse Recovery Current
- Positive temperature coefficient
- Temperature-independent performance
- High-speed switching
- Low switching loss
- Low heat dissipation requirements

#### SiC MOSFET Characteristic:

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Higher System Efficiency
- Reduced Cooling Requirements
- Increased System Switching Frequency

## **Bare Die**

Packageless, the chip is used in the module package or another package by our terminal client of semiconductor company.



# SMD

These SMD package device used in rectifier diode of Power Factor Correction in low power supply, 0~3000W, TV Power, other which concern with power, telephone charger, computer charger, new energy automobile DC/DC converter, and so forth.







DFN

TC

TO-263

## DIP

DIP package is a general market product, these chip used in a variety of PFC and rectifier circuits commonly, used in the markets are automotive OBC, DC-DC, charging pile, A/C inverter, PV inverter, server power supply, UPS, high-power LED power supply, etc.









TO-220

TO-247-2

47-2 TO-247-3

TO-247-4

## Module

The SBD module used in the high power supply, used in EV Supercharger, power supply for large industrial equipment etc.



SOT-277

